

ABSTRACT

RESIN SEALING APPARATUS AND METHOD OF DETECTING ABNORMALITY OF RESIN SEALING APPARATUS

Provided are a resin sealing apparatus and a method of detecting abnormality of a resin sealing apparatus which are capable of appropriately detecting whether a sliding defect of an exposing pin occurs in respect to a resin sealed package in which an exposed portion is formed at a surface of an electronic component.

The apparatus includes a first mold including a main body, a mold matching surface, a concave cavity portion, a first through and the hollow portion of the main body, a second through hole, a pin flange portion, an exposing pin, a to-be-detected pin and a detection sensor unit, a second mold including a mold matching surface, a mold drive unit and a load measuring loader including a detection loader main body and a load sensor unit.

Figure 1